

Amendments to the Specification begin on page 4 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 7 of this paper.

Remarks begin on page 16 of this paper.

IN THE TITLE:

The title has been amended herein. Pursuant to 37 C.F.R. §§ 1.121 and 1.125 (as amended to date), please enter the title as amended.

**TRANSFER MOLDING AND UNDERFILLING METHOD AND APPARATUS
INCLUDING ORIENTING THE ACTIVE SURFACE OF A
SEMICONDUCTOR SUBSTRATE ~~CHIP~~ SUBSTANTIALLY VERTICALLY**